

PTO/SB/08A
Substitute for Form PTO-1449

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet 1 of 5

Application Number 72804

Filing Date January 11, 2002

First Named Inventor Chason et al.

Art Unit 2811

Examiner Name Jones, J.

Attorney Docket 72804

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U.S. PATENT DOCUMENTS

| Examiner Initials* | Cite No. ¹ | Document Number | Publication Date MM-DD-YYYY | Name of Patentee or Applicant of Cited Document | Pages, Columns, Lines Where Relevant Passages or Relevant Figures Appear |
|-----------------------|--------------------------|-------------------------------|--------------------------------|--|--|
| | | Number-Kind Code ² | | | |
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| | | Country Code ³ -Number ⁴ -Kind Code ⁵ | | | | |
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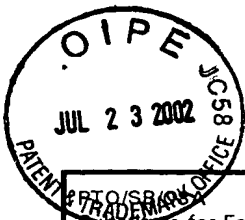
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| Sheet | 2 | of | 5 | Attorney Docket | 72804 |

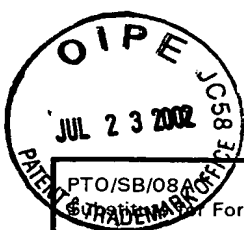
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| PTO/SB/08A Supplemental Form PTO-1449 | | Application Number | 72804 | | |
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| | | First Named Inventor | Chason et al. | | |
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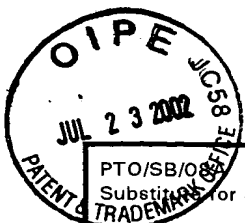
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| Examiner Initials* | Cite No. ¹ | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published | T ² |
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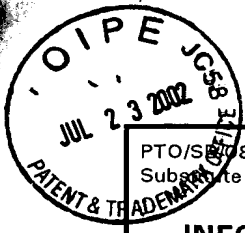
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| | | First Named Inventor | Chason et al. |
| | | Art Unit | 2811 |
| | | Examiner Name | Jones, J. |
| Sheet | 4 of 5 | Attorney Docket | 72804 |

| OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS | | |
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| Examiner Initials * | Cite No. ¹ | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published |
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